

**IN THE CLAIMS:**

Please replace the claims as follows (the status in accordance with the changes being made on this Amendment being presented below):

1. (Currently Amended) A printed circuit board arrangement comprising:  
a core substrate having a cavity, and  
a resin insulating layer and a conductor circuit laminated on the core substrate,  
an IC chip mounted on an outer layer of the conductor circuit, the IC chip being connected via a solder bump located under the IC chip and  
a plurality of capacitors accommodated in the cavity, the capacitors being located immediately below the IC chip.
2. (Currently Amended) A printed circuit board arrangement according to claim 1, wherein a resin is charged between the plurality of capacitors in the cavity, and the resin has a thermal expansion coefficient smaller than a thermal expansion coefficient of the core substrate.
3. (Currently Amended) A printed circuit board arrangement according to claim 1 or 2, wherein the resin layer has through holes.
4. (Currently Amended) A printed circuit board arrangement according to claim 1 or 2, wherein a metal film is formed on electrodes of the capacitor, and an electric connection for the electrodes formed with the metal film is established by plating.

5. (Currently Amended) A printed circuit board arrangement according to claim 4, wherein the metal film formed on the electrodes of the chip capacitor is a plated film including copper as a main component.

6. (Previously Presented) A printed circuit board arrangement comprising:  
a core substrate having a cavity therein, and  
a resin insulating layer and a conductor circuit laminated on the core substrate, and  
a plurality of capacitors accommodated in the cavity, wherein at least a part of electrodes of each capacitor is uncoated with a coating layer and exposed to the outside, and an electric connection for the electrode exposed from the coating layer is established by plating.

7. (Currently Amended/Withdrawn) A printed circuit board arrangement according to ~~any one of claims 1 to 6~~, wherein each of the plurality of capacitors is a chip capacitor in which having electrodes are formed along an inside of the an outer edge thereof is used.

8. (Currently Amended/Withdrawn) A printed circuit board arrangement according to ~~any one of claims 1 to 8~~ claim 6, wherein each of the plurality of capacitors is a chip capacitor in which having electrodes are formed in matrix is used.

9. (Currently Amended/Withdrawn) A printed circuit board arrangement according to ~~any one of claims 1 to 8~~ claim 6, wherein ~~a capacitor is~~ the plurality of capacitors are mounted on the surface of the printed circuit board.

10. – 78. (Cancelled)